CHIPQUIK® NI3300-10M

Datasheet revision 1.0 www.chipquik.com

REH1 Water-Soluble Nickel Tack Flux in 10cc/10g Syringe w/plunger and tips



Product Highlights

Water-Soluble Tacky Flux for Nickel Soldering
Higher Activity (REH1)
Better Wetting
Designed for Hard to Solder Surfaces including:
- **Nickel**
- **Nickel Plated Copper**
- **Copper**

Water-Soluble, Remove with Hot Water (60°C+) after soldering
RoHS 3 and REACH compliant

Specifications

Flux Type:	Synthetic Water-Soluble (for Leaded and Lead-Free applications)
Flux Classification:	REH1 (Must be cleaned off post-use using Hot Water (60°C+), Flux Remover or IPA)
Flux Activation Temperature:	140°C (284°F)
Packaging:	10cc/10g Luer Lock Manual Syringe
Shelf Life:	Refrigerated >24 months, Unrefrigerated >24 months

Stencil Life

>8 hours @ 20-50% RH 22-28°C (72-82°F)
>4 hours @ 50-70% RH 22-28°C (72-82°F)

Stencil Cleaning

Automated stencil cleaning systems for both stencil and misprinted boards. Manual cleaning using isopropyl alcohol (IPA).

Storage and Handling

Store refrigerated or at room temperature 3-25°C (37-77°F). Do not freeze. Allow 4 hours for flux to reach an operating temperature of 20-25°C (68-77°F) before use.

Transportation

This product has no shipping restrictions. Shipping below 0°C (32°F) or above 25°C (77°F) for normal transit times by ground or air will not impact this product's stated shelf life.

Conforms to the following Industry Standards:

J-STD-004B, Amendment 1 (Solder Fluxes):	Yes
RoHS 3 Directive (EU) 2015/863:	Yes

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